



IFW 2823

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: Mostafazadeh et al.

Attorney Docket No.:  
NSC1P226R/P03856R1

Application No.: 10/016,750

Examiner: Unassigned

Filed: December 10, 2001

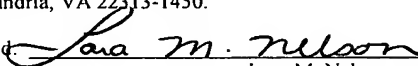
Group: Unassigned

Title: LEAD FRAME DESIGN FOR  
INCREASED CHIP PINOUT

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on September 1, 2004 in an envelope addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

Signed:

  
Lara M. Nelson

**REQUEST FOR STATUS**


Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Applicant hereby requests status of the above-referenced patent application. This application was filed on December 10, 2001, and no response has been received as of this date.

Respectfully submitted,

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